

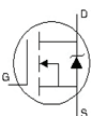
Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	150	—	—	V	V _{GS} = 0V, I _D = 250μA
ΔV _{(BR)DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient	—	0.17	—	V/°C	Reference to 25°C, I _D = 5mA ①
R _{DS(on)}	Static Drain-to-Source On-Resistance	—	4.8	5.9	mΩ	V _{GS} = 10V, I _D = 103A ④
V _{GS(th)}	Gate Threshold Voltage	3.0	—	5.0	V	V _{DS} = V _{GS} , I _D = 250μA
g _{fs}	Forward Trans conductance	162	—	—	S	V _{DS} = 50V, I _D = 103A
R _G	Internal Gate Resistance	—	1.0	—	Ω	
I _{DSS}	Drain-to-Source Leakage Current	—	—	20	μA	V _{DS} = 150V, V _{GS} = 0V
		—	—	250	μA	V _{DS} = 150V, V _{GS} = 0V, T _J = 125°C
I _{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	V _{GS} = 20V
	Gate-to-Source Reverse Leakage	—	—	-100	nA	V _{GS} = -20V

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

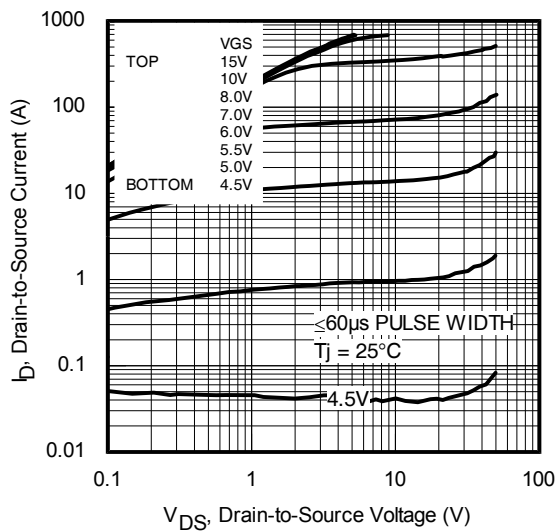
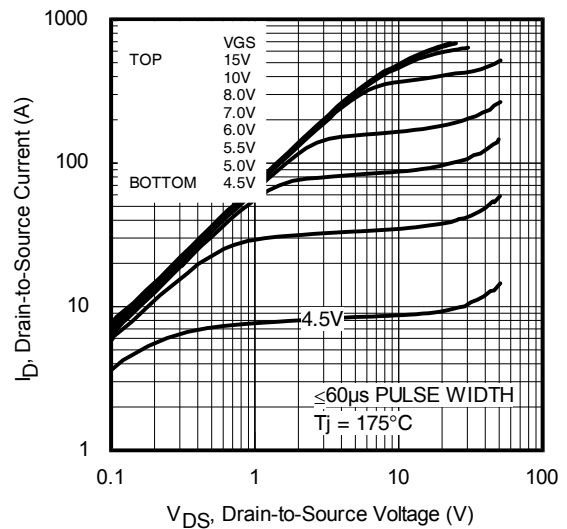
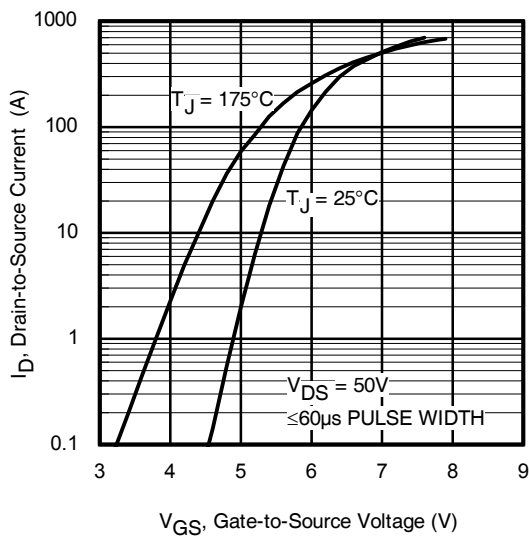
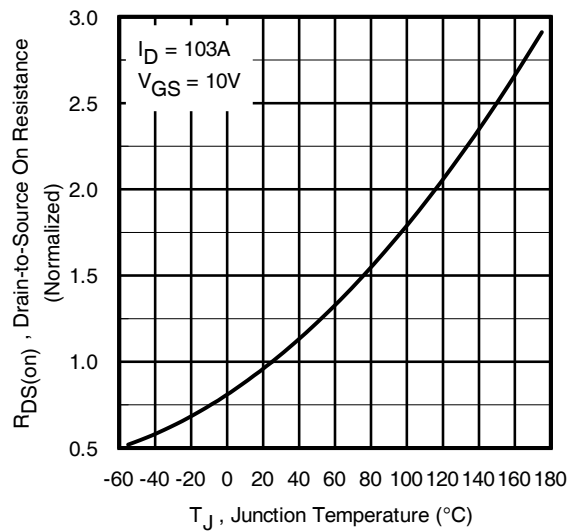
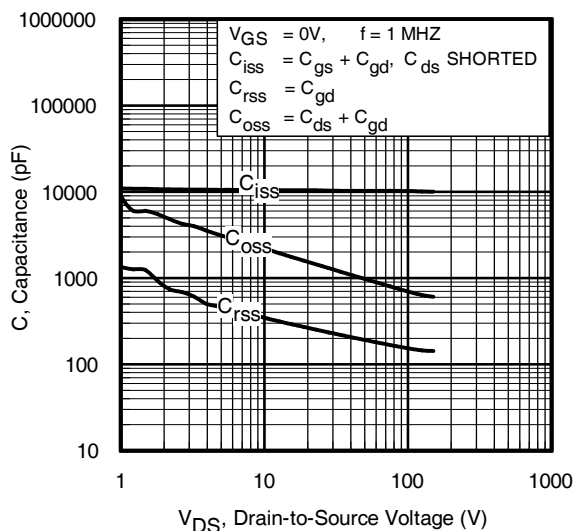
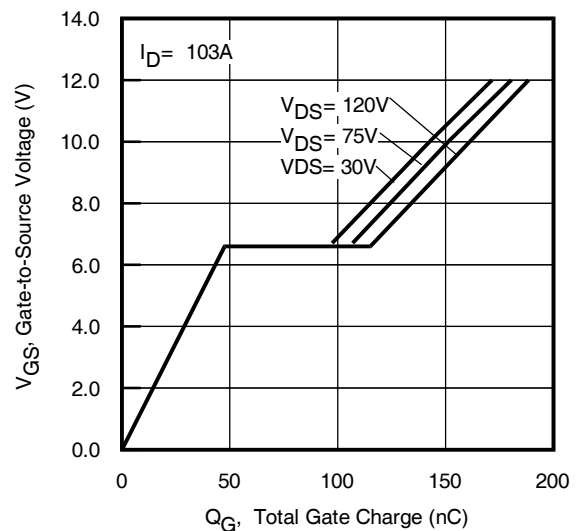
Q _g	Total Gate Charge	—	151	227	nC	I _D = 103A V _{DS} = 75V V _{GS} = 10V ④
Q _{gs}	Gate-to-Source Charge	—	52	—		
Q _{gd}	Gate-to-Drain Charge	—	55	—		
Q _{sync}	Total Gate Charge Sync. (Q _g – Q _{gd})	—	96	—		
t _{d(on)}	Turn-On Delay Time	—	27	—	ns	V _{DD} = 98V I _D = 103A R _G = 1.0Ω V _{GS} = 10V ④
t _r	Rise Time	—	119	—		
t _{d(off)}	Turn-Off Delay Time	—	47	—		
t _f	Fall Time	—	84	—		
C _{iss}	Input Capacitance	—	10470	—	pF	V _{GS} = 0V V _{DS} = 50V f = 1.0MHz, See Fig. 5 V _{GS} = 0V, V _{DS} = 0V to 120V (see fig.11) ⑥
C _{oss}	Output Capacitance	—	977	—		
C _{rss}	Reverse Transfer Capacitance	—	203	—		
C _{oss eff. (ER)}	Effective Output Capacitance (Energy Related)	—	897	—		
C _{oss eff. (TR)}	Effective Output Capacitance (Time Related)	—	1272	—		V _{GS} = 0V, V _{DS} = 0V to 120V ⑤

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)	—	—	171	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I _{SM}	Pulsed Source Current (Body Diode) ①	—	—	684		
V _{SD}	Diode Forward Voltage	—	—	1.3	V	T _J = 25°C, I _S = 103A, V _{GS} = 0V ④
t _{rr}	Reverse Recovery Time	—	110	—	ns	T _J = 25°C T _J = 125°C V _R = 100V
		—	133	—		
Q _{rr}	Reverse Recovery Charge	—	515	—	nC	T _J = 25°C T _J = 125°C I _F = 103A di/dt = 100A/μs ④
		—	758	—		
I _{RRM}	Reverse Recovery Current	—	8.8	—	A	T _J = 25°C
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L _S +L _D)				

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by T_{Jmax}, starting T_J = 25°C, L = 0.144mH, R_G = 25Ω, I_{AS} = 103A, V_{GS} = 10V. Part not recommended for use above this value.
- ③ I_{SD} ≤ 103A, di/dt ≤ 360A/μs, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 175°C.
- ④ Pulse width ≤ 400μs; duty cycle ≤ 2%.
- ⑤ C_{oss eff. (TR)} is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.
- ⑥ C_{oss eff. (ER)} is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.
- ⑦ R_θ is measured at T_J of approximately 90°C.


Fig. 1 Typical Output Characteristics

Fig. 2 Typical Output Characteristics

Fig. 3 Typical Transfer Characteristics

Fig. 4 Normalized On-Resistance vs. Temperature

Fig. 5. Typical Capacitance vs. Drain-to-Source Voltage

Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage

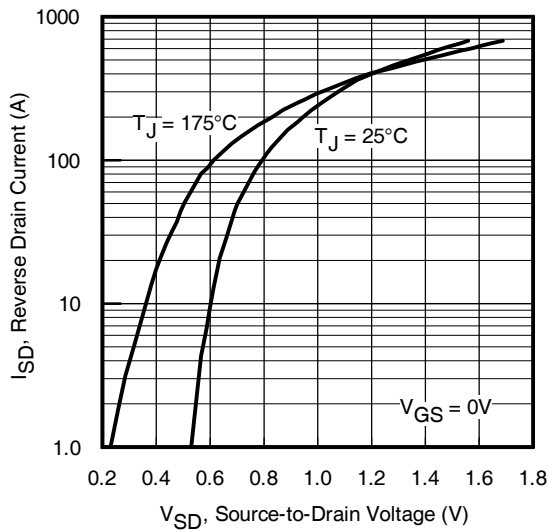


Fig. 7 Typical Source-to-Drain Diode Forward Voltage

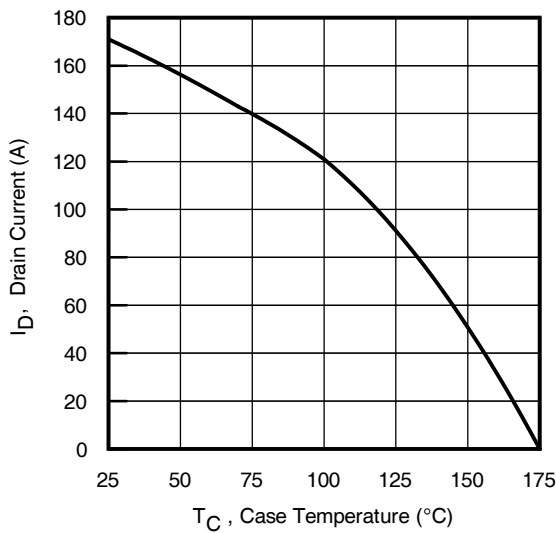


Fig 9. Maximum Drain Current vs. Case Temperature

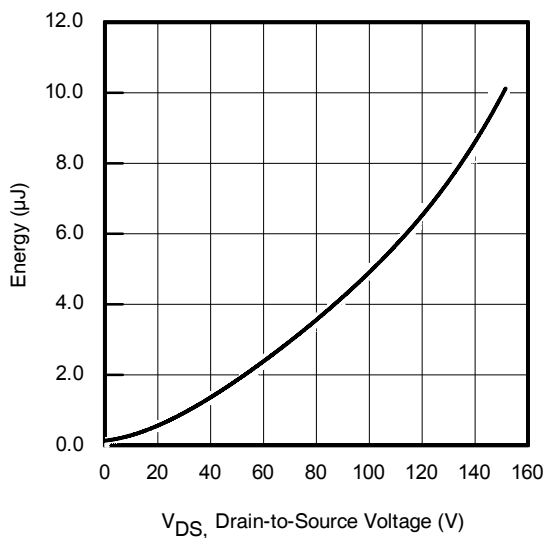


Fig 11. Typical Coss Stored Energy

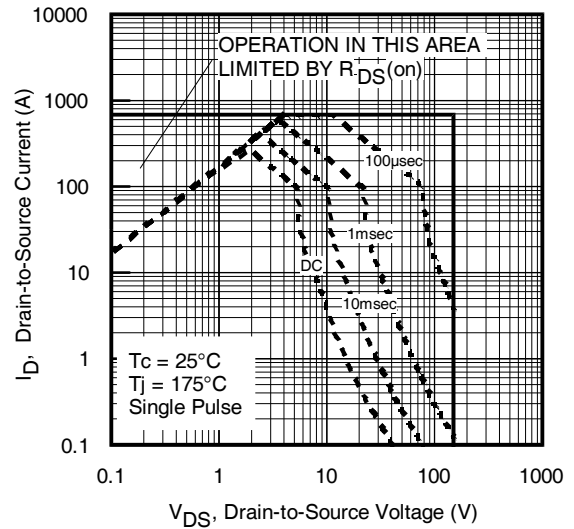


Fig 8. Maximum Safe Operating Area

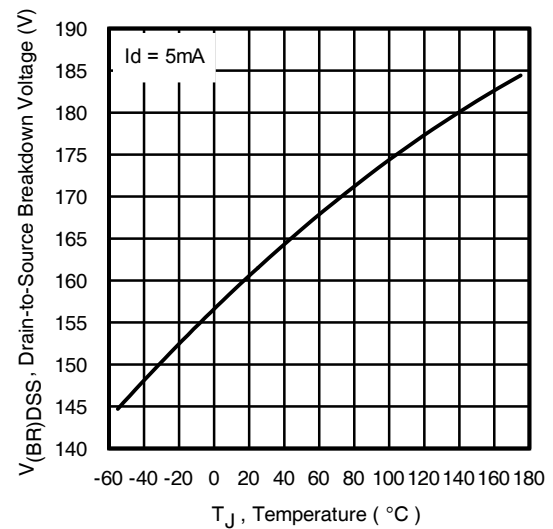


Fig 10. Drain-to-Source Breakdown Voltage

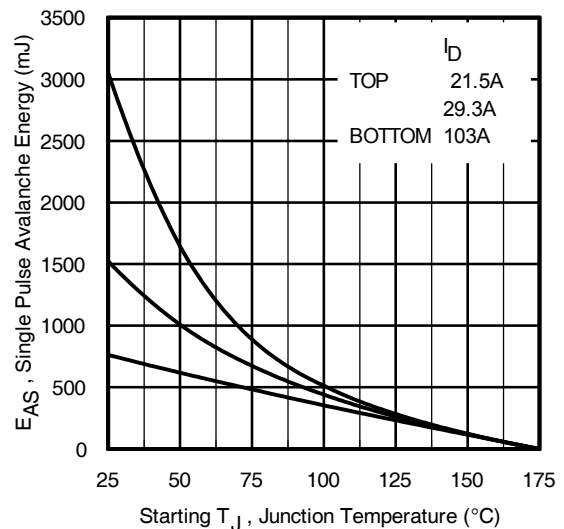


Fig 12. Maximum Avalanche Energy vs. Drain Current

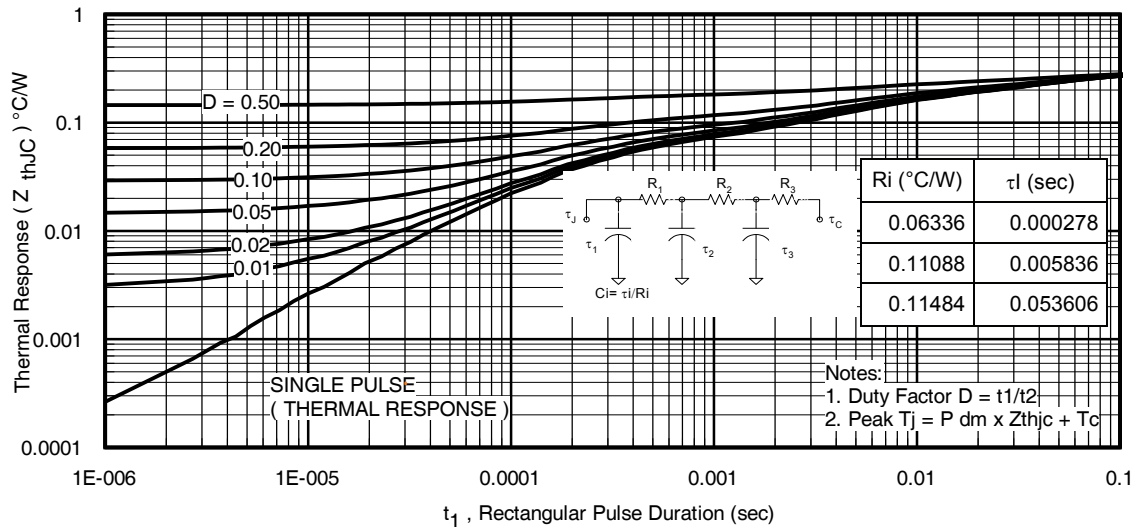


Fig 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case

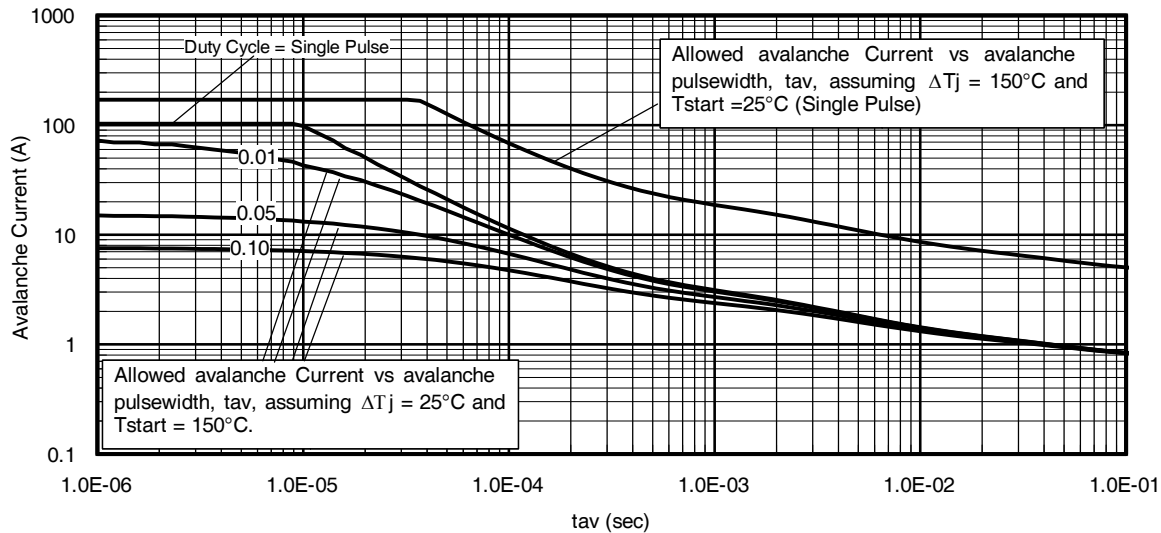


Fig 14. Avalanche Current vs. Pulse width

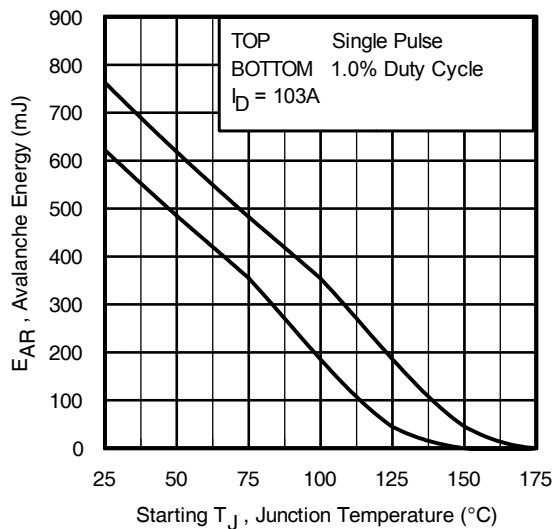


Fig 15. Maximum Avalanche Energy vs. Temperature

Notes on Repetitive Avalanche Curves , Figures 14, 15:
 (For further info, see AN-1005 at www.infineon.com)

1. Avalanche failures assumption:
Purely a thermal phenomenon and failure occurs at a temperature far in excess of T_{jmax} . This is validated for every part type.
2. Safe operation in Avalanche is allowed as long as T_{jmax} is not exceeded.
3. Equation below based on circuit and waveforms shown in Figures 22a, 22b.
4. $P_{D(ave)}$ = Average power dissipation per single avalanche pulse.
5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
6. I_{av} = Allowable avalanche current.
7. ΔT = Allowable rise in junction temperature, not to exceed T_{jmax} (assumed as 25°C in Figure 14, 15).
 t_{av} = Average time in avalanche.
 D = Duty cycle in avalanche = $t_{av} \cdot f$
 $Z_{thJC}(D, t_{av})$ = Transient thermal resistance, see Figures 13)

$$P_{D(ave)} = \frac{1}{2} (1.3 \cdot BV \cdot I_{av}) = \frac{\Delta T}{Z_{thJC}}$$

$$I_{av} = \frac{2 \Delta T}{1.3 \cdot BV \cdot Z_{thJC}}$$

$$E_{AS(AR)} = P_{D(ave)} \cdot t_{av}$$

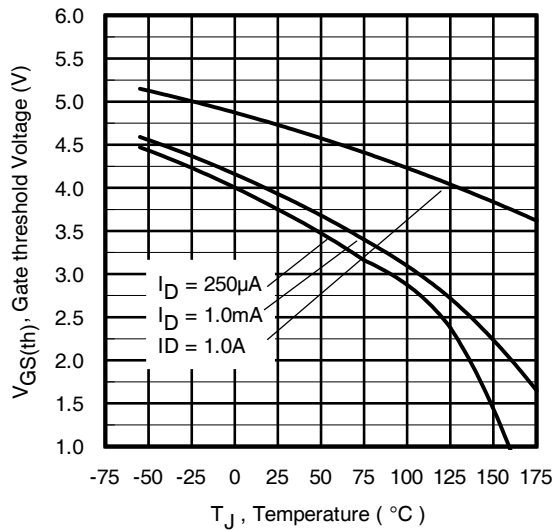


Fig. 16. Threshold Voltage vs. Temperature

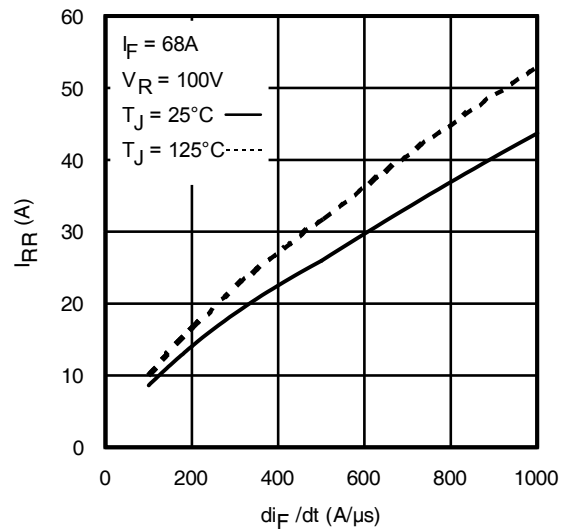


Fig. 17 - Typical Recovery Current vs. di/dt

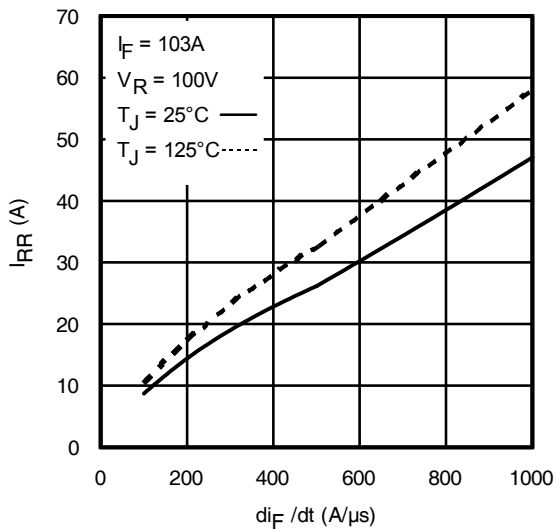


Fig. 18 - Typical Recovery Current vs. di/dt

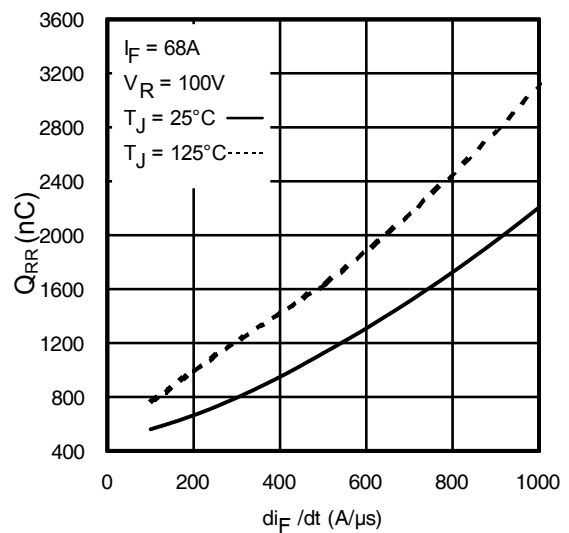


Fig. 19 - Typical Stored Charge vs. di/dt

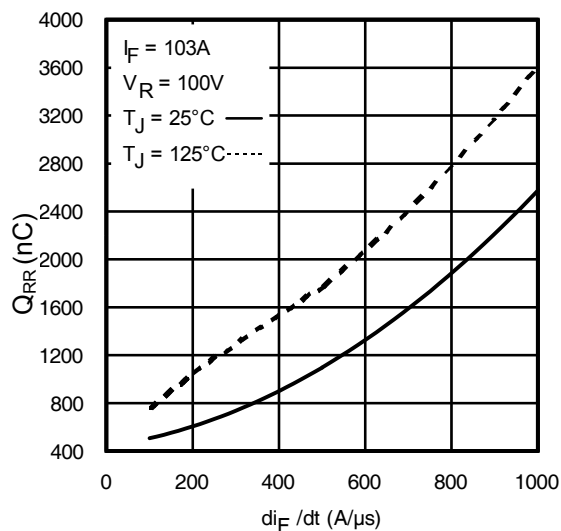
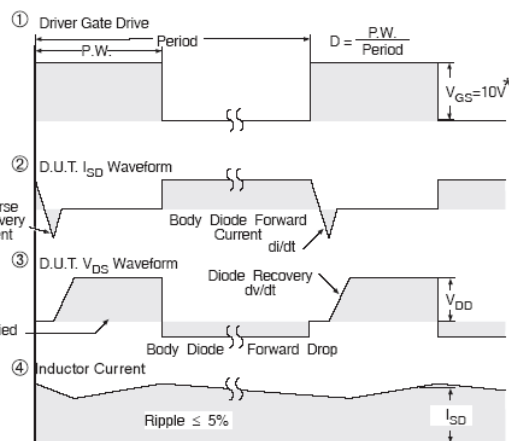
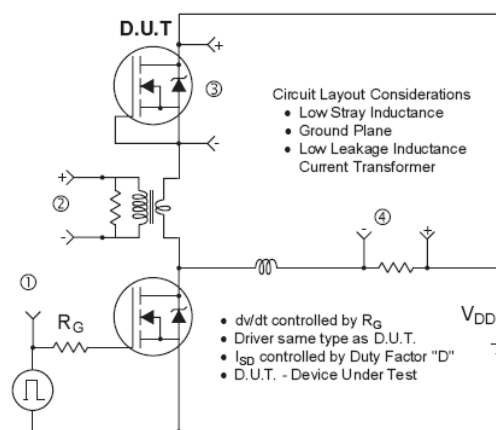


Fig. 20 - Typical Stored Charge vs. di/dt



* $V_{GS} = 5V$ for Logic Level Devices

Fig 21. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

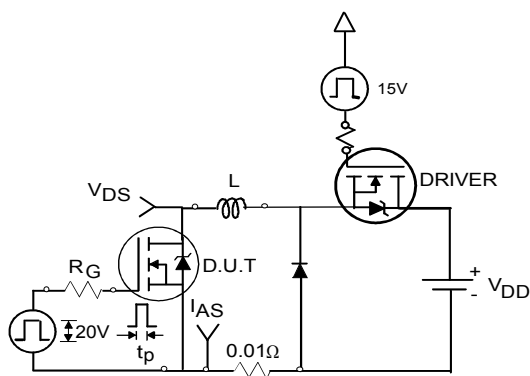


Fig 22a. Unclamped Inductive Test Circuit

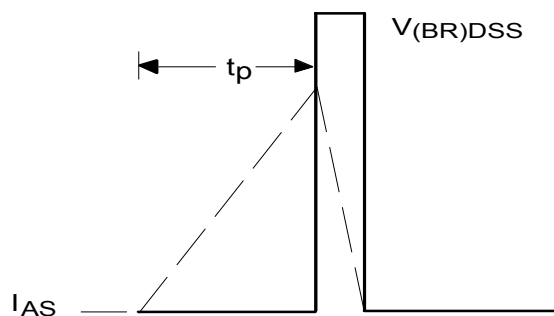


Fig 22b. Unclamped Inductive Waveforms

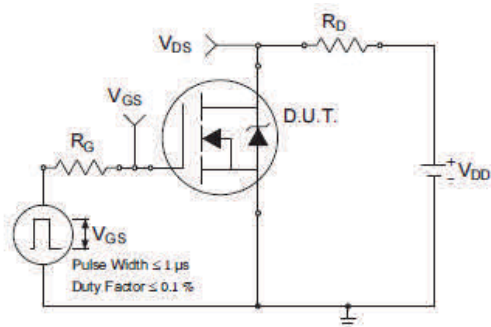


Fig 23a. Switching Time Test Circuit

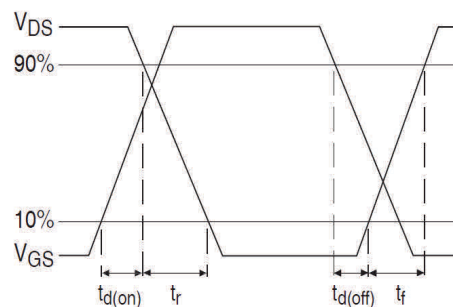


Fig 23b. Switching Time Waveforms

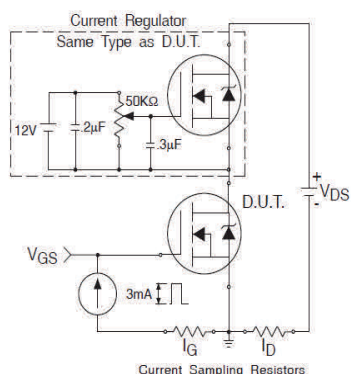


Fig 24a. Gate Charge Test Circuit

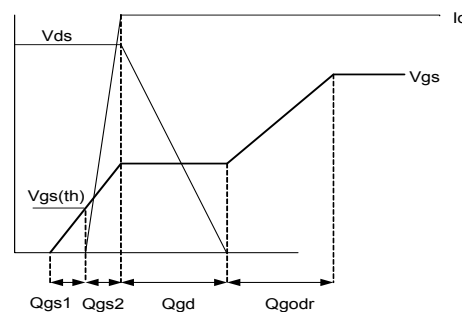
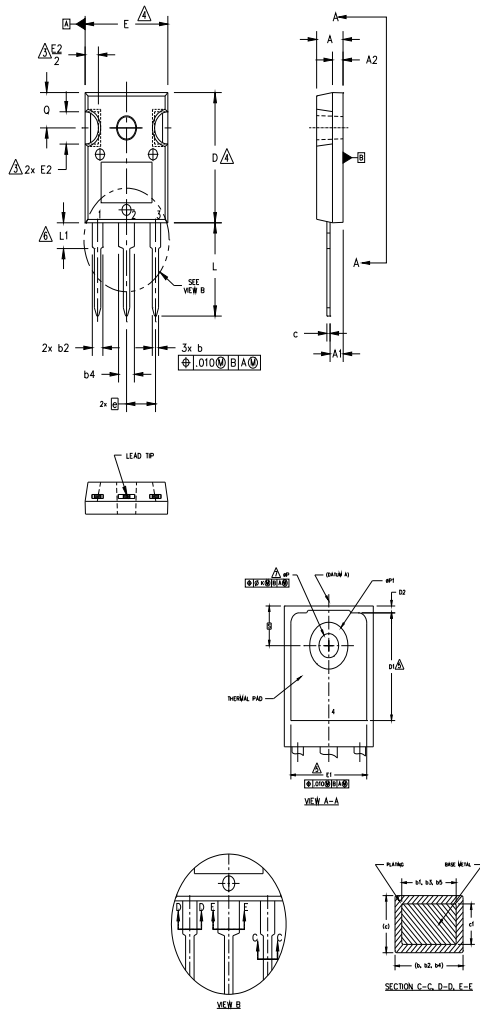


Fig 24b. Gate Charge Waveform

TO-247AC Package Outline (Dimensions are shown in millimeters (inches))



NOTES:

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M 1994.
2. DIMENSIONS ARE SHOWN IN INCHES.
3. CONTOUR OF SLOT OPTIONAL.
4. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS D1 & E1.
6. LEAD FINISH UNCONTROLLED IN L1.
7. ØP TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5 ° TO THE TOP OF THE PART WITH A MAXIMUM HOLE DIAMETER OF .154 INCH.
8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-247AC .

SYMBOL	DIMENSIONS				NOTES
	INCHES		MILLIMETERS		
	MIN.	MAX.	MIN.	MAX.	
A	.183	.209	4.65	5.31	4
A1	.087	.102	2.21	2.59	
A2	.059	.098	1.50	2.49	
b	.039	.055	0.99	1.40	
b1	.039	.053	0.99	1.35	
b2	.065	.094	1.65	2.39	
b3	.065	.092	1.65	2.34	
b4	.102	.135	2.59	3.43	
b5	.102	.133	2.59	3.38	
c	.015	.035	0.38	0.89	
c1	.015	.033	0.38	0.84	5
D	.776	.815	19.71	20.70	
D1	.515	—	13.08	—	
D2	.020	.053	0.51	1.35	
E	.602	.625	15.29	15.87	
E1	.530	—	13.46	—	
E2	.178	.216	4.52	5.49	
e	.215 BSC		5.46 BSC		
Øk	.010		0.25		
L	.559	.634	14.20	16.10	
L1	.146	.169	3.71	4.29	
ØP	.140	.144	3.56	3.66	
ØP1	—	.291	—	7.39	
Q	.209	.224	5.31	5.69	
S	.217 BSC		5.51 BSC		

LEAD ASSIGNMENTS

HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

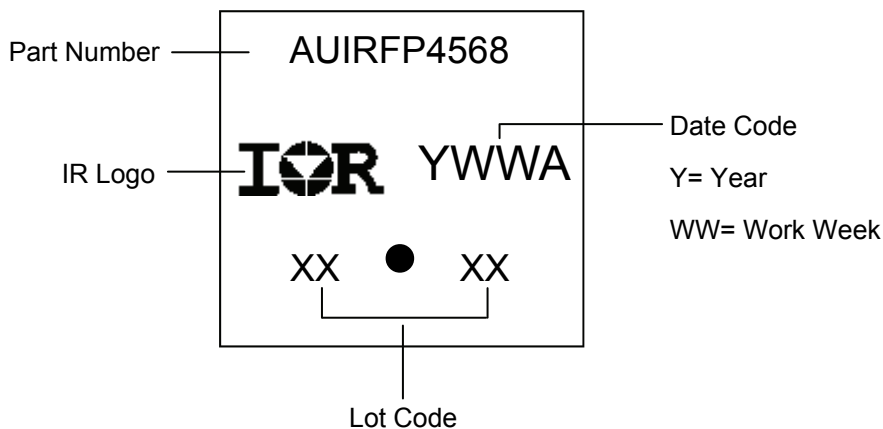
IGBTs, CoPACK

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

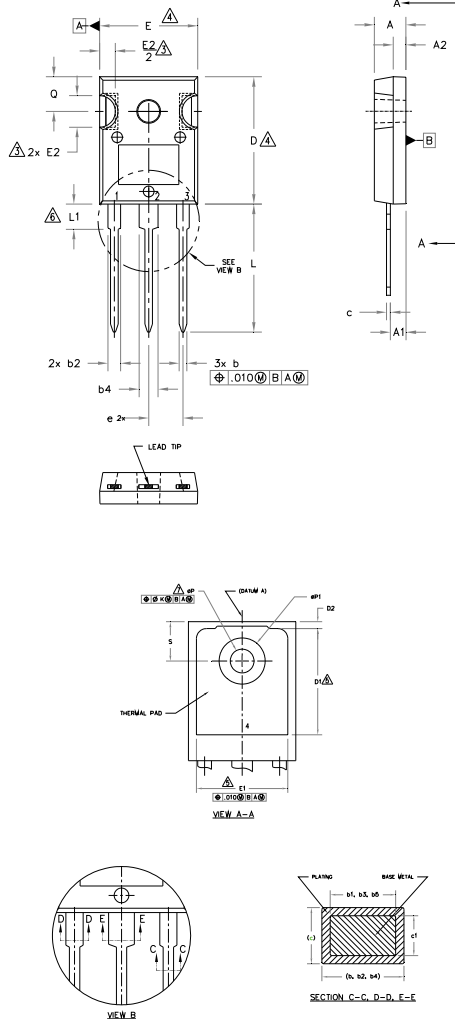
DIODES

- 1.- ANODE/OPEN
- 2.- CATHODE
- 3.- ANODE

TO-247AC Part Marking Information



Long Lead TO-247AC Package Outline (Dimensions are shown in millimeters (inches))



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A1	.087	.102	2.21	2.59		
A2	.059	.098	1.50	2.49		
b	.039	.055	0.99	1.40		
b1	.039	.053	0.99	1.35		
b2	.065	.094	1.65	2.39		
b3	.065	.092	1.65	2.34		
b4	.102	.135	2.59	3.43		
b5	.102	.133	2.59	3.38		
c	.015	.035	0.38	0.89		
c1	.015	.033	0.38	0.84	4	
D	.776	.815	19.71	20.70		
D1	.515	—	13.08	—		5
D2	.020	.053	0.51	1.35		
E	.602	.625	15.29	15.87	4	
E1	.530	—	13.46	—		
E2	.178	.216	4.52	5.49		
e	.215 BSC		5.46 BSC			
øk	.010		0.25			
L	.780	.827	19.57	21.00		
L1	.146	.169	3.71	4.29		
øP	.140	.144	3.56	3.66		
øP1	—	.291	—	7.39		
Q	.209	.224	5.31	5.69		
S	.217 BSC		5.51 BSC			

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HEXFET

1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

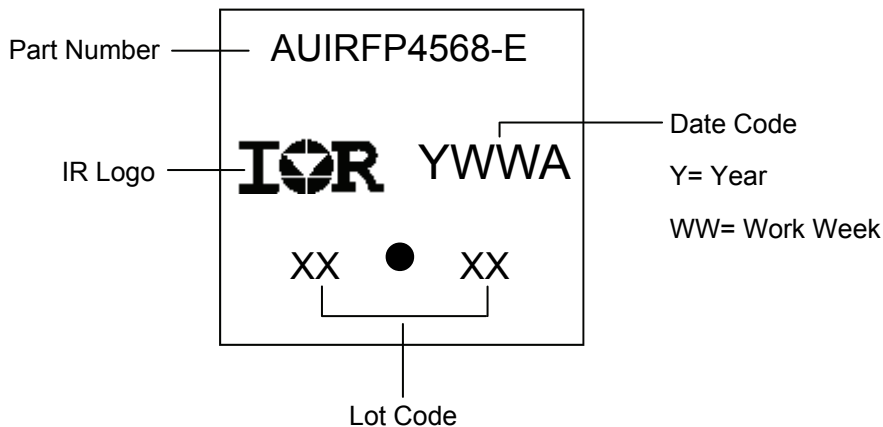
IGBTs, CoPACK

1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

DIODES

1. ANODE/OPEN
2. CATHODE
3. ANODE

Long Lead TO-247AC Part Marking Information



Qualification Information

Qualification Level		Automotive (per AEC-Q101)	
		Comments: This part number(s) passed Automotive qualification. Infineon's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level		TO-247AC	N/A
		Long Lead TO-247AC	
ESD	Machine Model	Class M4 (+/- 800V) [†] AEC-Q101-002	
	Human Body Model	Class H3A (+/- 6000V) [†] AEC-Q101-001	
	Charged Device Model	Class C5 (+/- 2000V) [†] AEC-Q101-005	
RoHS Compliant		Yes	

† Highest passing voltage.

Revision History

Date	Comments
10/21/2015	- Updated datasheet with corporate template - Removed obsolete parts "AUIRFP4568E" on all pages - Corrected ordering table on page 1.
4/29/2019	Added AUIRFP4568-E (Long Lead TO-247AC)package –all pages

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